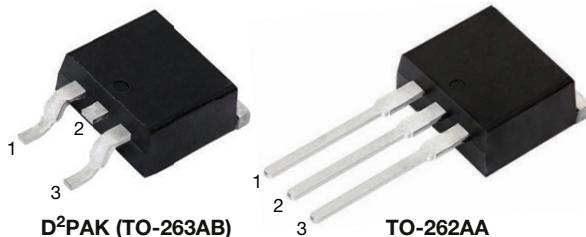
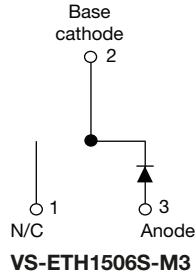
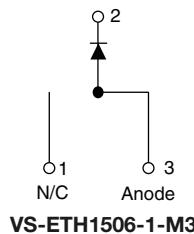


## Hyperfast Rectifier, 15 A FRED Pt®


**D<sup>2</sup>PAK (TO-263AB)**
**TO-262AA**

**VS-ETH1506S-M3**

**VS-ETH1506-1-M3**

### FEATURES

- Hyperfast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- Designed and qualified according to JEDEC®-JESD 47
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
FREE

### DESCRIPTION / APPLICATIONS

Hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

PRIMARY CHARACTERISTICS	
I <sub>F(AV)</sub>	15 A
V <sub>R</sub>	600 V
V <sub>F</sub> at I <sub>F</sub>	1.25 V
t <sub>rr</sub> (typ.)	21 ns
T <sub>J</sub> max.	175 °C
Package	D <sup>2</sup> PAK (TO-263AB), TO-262AA
Circuit configuration	Single

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Repetitive peak reverse voltage	V <sub>RRM</sub>		600	V	
Average rectified forward current	I <sub>F(AV)</sub>	T <sub>C</sub> = 139 °C	15	A	
Non-repetitive peak surge current	I <sub>FSM</sub>	T <sub>C</sub> = 25 °C	160		
Operating junction and storage temperatures	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +175	°C	

ELECTRICAL SPECIFICATIONS (T <sub>J</sub> = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V <sub>BR</sub> , V <sub>R</sub>	I <sub>R</sub> = 100 µA	600	-	-	V
Forward voltage		I <sub>F</sub> = 15A		1.8	2.45	
	V <sub>F</sub>	I <sub>F</sub> = 15 A, T <sub>J</sub> = 150 °C	-	1.25	1.6	
Reverse leakage current		V <sub>R</sub> = V <sub>R</sub> rated		0.01	15	
	I <sub>R</sub>	T <sub>J</sub> = 150 °C, V <sub>R</sub> = V <sub>R</sub> rated	-	20	200	µA
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 600 V		12	-	
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body	-	8.0	-	nH

**DYNAMIC RECOVERY CHARACTERISTICS** ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1.0 \text{ A}$ , $dI_F/dt = 100 \text{ A}/\mu\text{s}$ , $V_R = 30 \text{ V}$	-	21	26	ns
		$I_F = 15 \text{ A}$ , $dI_F/dt = 100 \text{ A}/\mu\text{s}$ , $V_R = 30 \text{ V}$	-	25	36	
		$T_J = 25^\circ\text{C}$	-	29	-	
		$T_J = 125^\circ\text{C}$	-	65	-	
Peak recovery current	$I_{RRM}$	$T_J = 25^\circ\text{C}$	-	3.9	-	A
		$T_J = 125^\circ\text{C}$	-	7.0	-	
Reverse recovery charge	$Q_{rr}$	$T_J = 25^\circ\text{C}$	-	60	-	nC
		$T_J = 125^\circ\text{C}$	-	240	-	
Reverse recovery time	$t_{rr}$	$T_J = 125^\circ\text{C}$	-	42	-	ns
Peak recovery current	$I_{RRM}$		-	21	-	A
Reverse recovery charge	$Q_{rr}$		-	480	-	nC

**THERMAL - MECHANICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	$T_J$ , $T_{Stg}$		-55	-	175	°C
Thermal resistance, junction to case	$R_{thJC}$		-	1.3	1.51	°C/W
Thermal resistance, junction to ambient	$R_{thJA}$	Typical socket mount	-	-	70	
Thermal resistance, case to heatsink	$R_{thCS}$	Mounting surface, flat, smooth, and greased	-	0.5	-	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style D <sup>2</sup> PAK (TO-263AB)	ETH1506S			
		Case style TO-262AA	ETH1506-1			

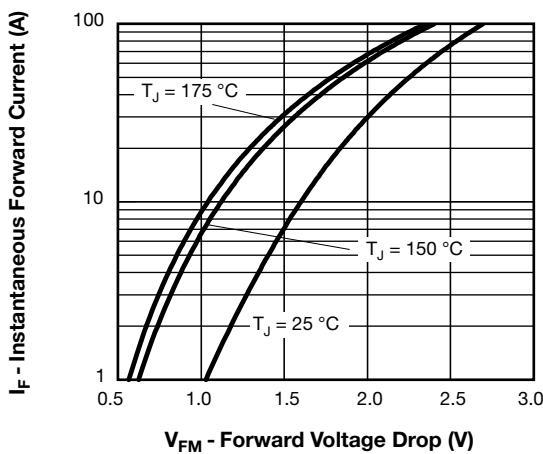


Fig. 1 - Maximum Forward Voltage Drop Characteristics

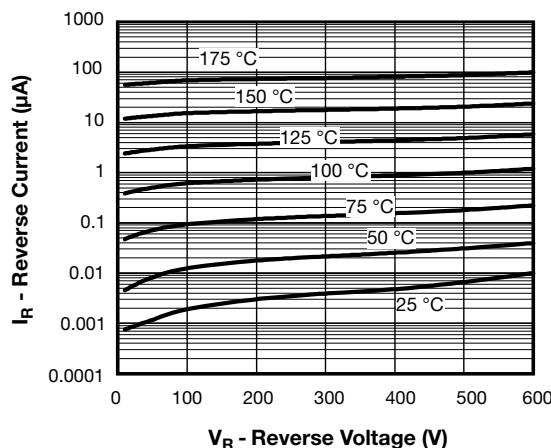


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

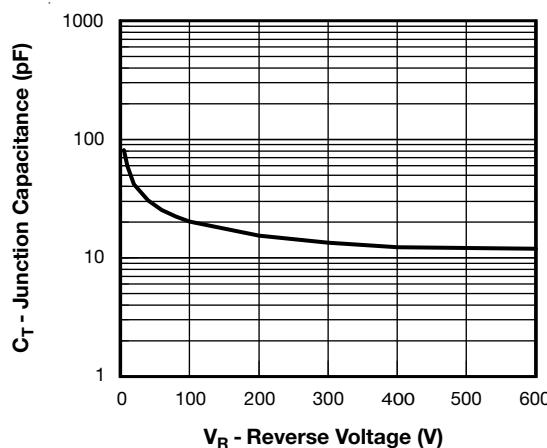


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

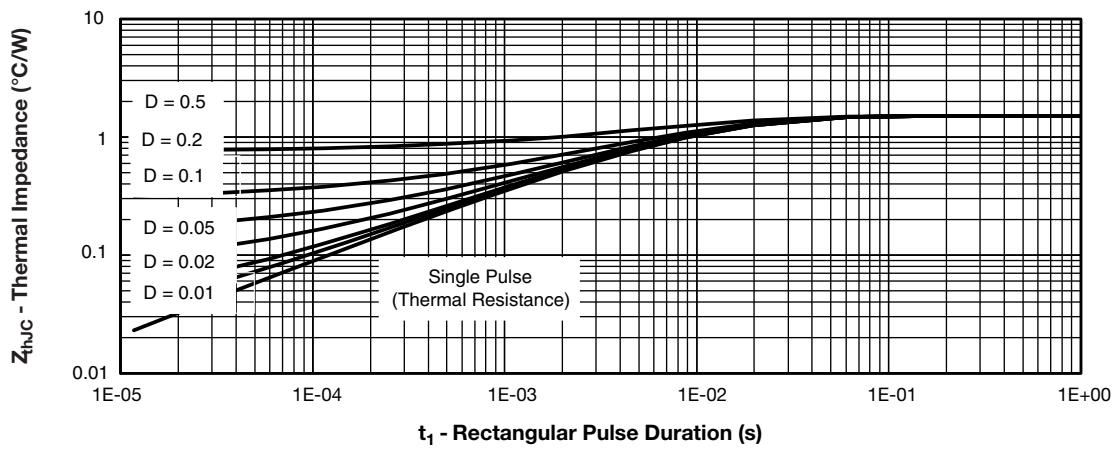


Fig. 4 - Max. Thermal Impedance  $Z_{thJC}$  Characteristics

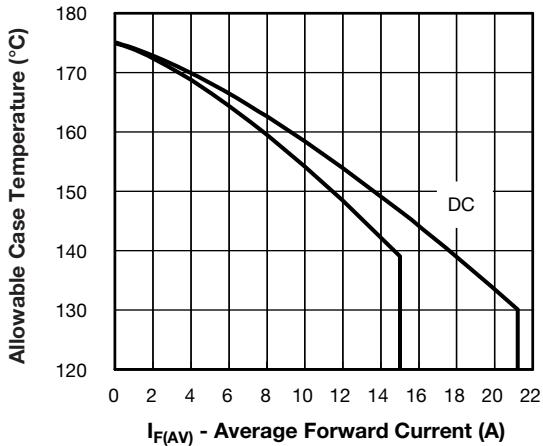


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

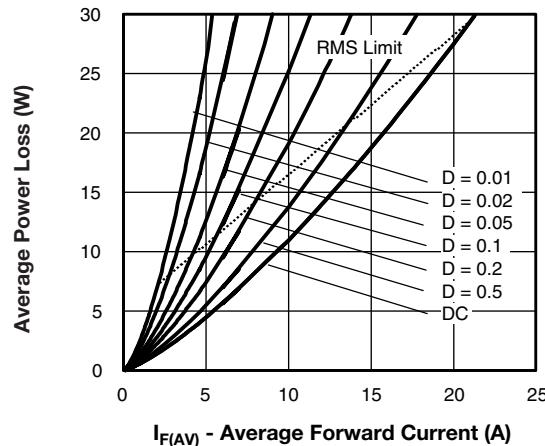


Fig. 6 - Forward Power Loss Characteristics

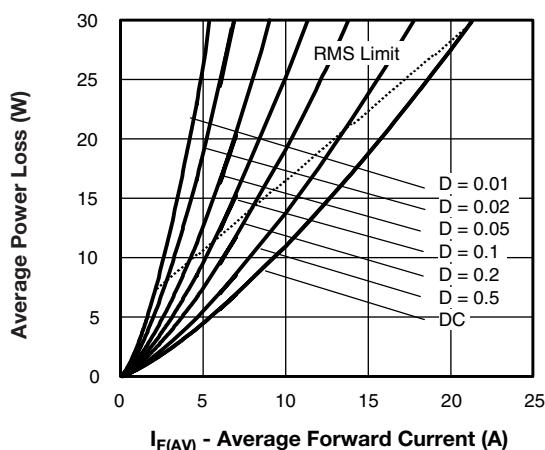


Fig. 7 - Typical Reverse Recovery Time vs.  $di_F/dt$

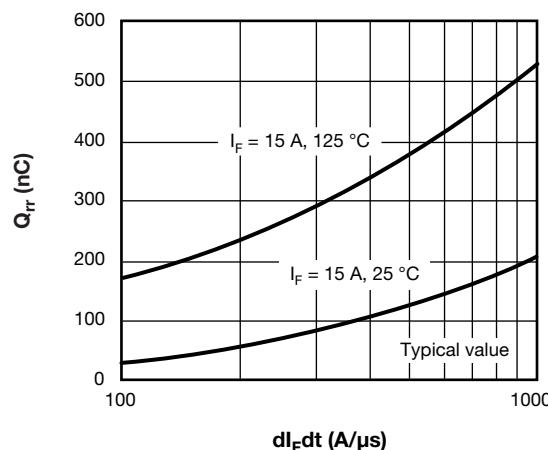
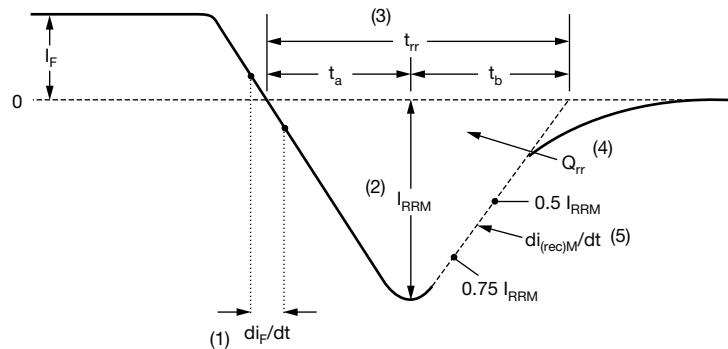


Fig. 8 - Typical Stored Charge vs.  $di_F/dt$



- (1)  $di_F/dt$  - rate of change of current through zero crossing
- (2)  $I_{RRM}$  - peak reverse recovery current
- (3)  $t_{rr}$  - reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through  $0.75 I_{RRM}$  and  $0.50 I_{RRM}$  extrapolated to zero current.

- (4)  $Q_{rr}$  - area under curve defined by  $t_{rr}$  and  $I_{RRM}$
- (5)  $di_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 9 - Reverse Recovery Waveform and Definitions

**ORDERING INFORMATION TABLE**

Device code	VS-	E	T	H	15	06	S	TRL	-M3
	(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)

- [1]** - Vishay Semiconductors product
- [2]** - Circuit configuration  
E = single
- [3]** - T = TO-220
- [4]** - H = hyperfast recovery time
- [5]** - Current code (15 = 15 A)
- [6]** - Voltage code (06 = 600 V)
- [7]** - • S = D<sup>2</sup>PAK (TO-263AB)
  - • -1 = TO-262AA
- [8]** - • None = tube (50 pieces)
  - • TRL = tape and reel (left oriented, for D<sup>2</sup>PAK (TO-263AB) package)
  - • TRR = tape and reel (right oriented, for D<sup>2</sup>PAK (TO-263AB) package)
- [9]** - -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

**ORDERING INFORMATION** (Example)

PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-ETH1506S-M3	50	Antistatic plastic tubes
VS-ETH1506STRR-M3	800	13" diameter plastic tape and reel
VS-ETH1506STRL-M3	800	13" diameter plastic tape and reel
VS-ETH1506-1-M3	50	Antistatic plastic tubes

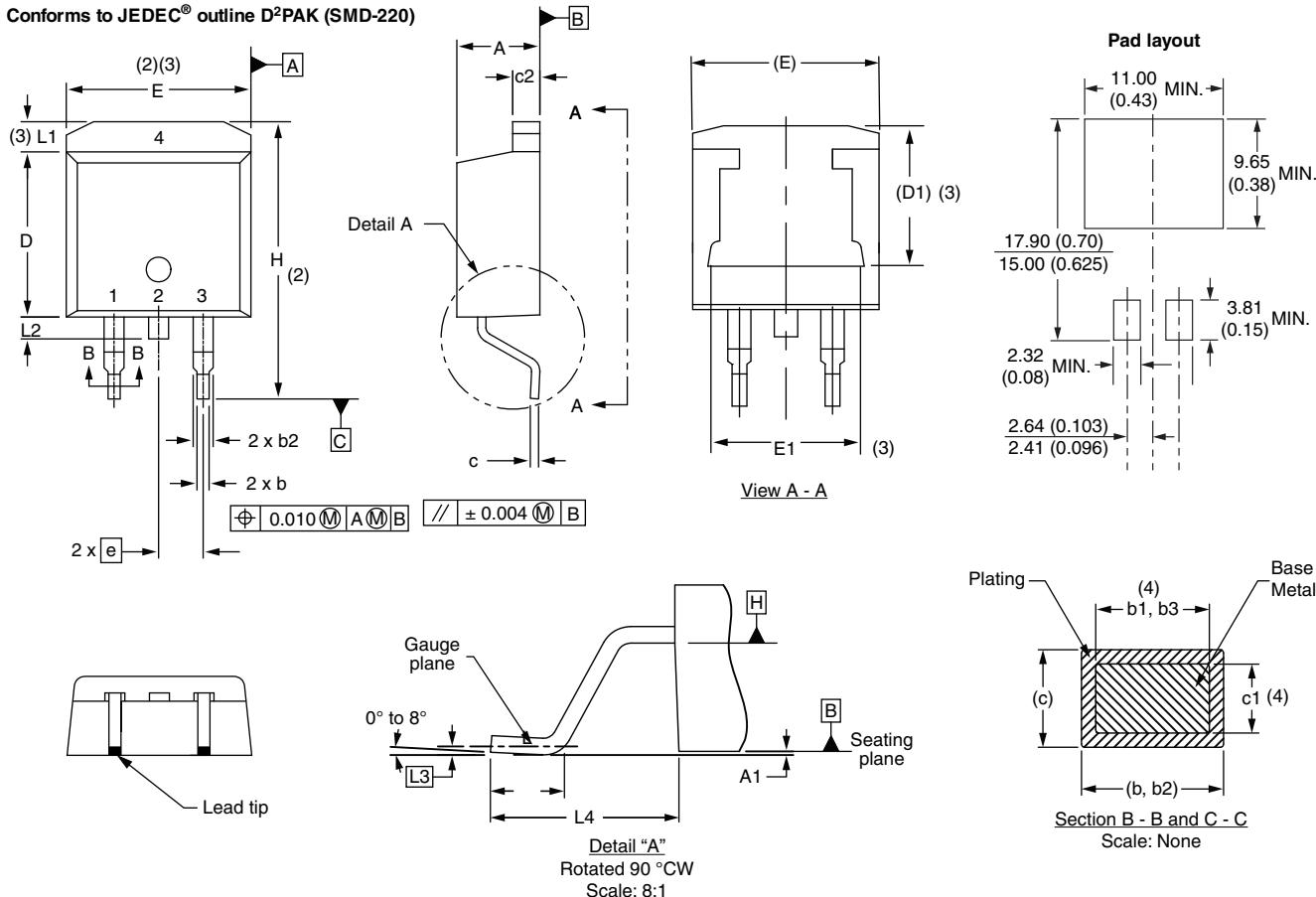
**LINKS TO RELATED DOCUMENTS**

Dimensions	D <sup>2</sup> PAK (TO-263AB)	<a href="http://www.vishay.com/doc?96164">www.vishay.com/doc?96164</a>
	TO-262AA	<a href="http://www.vishay.com/doc?96165">www.vishay.com/doc?96165</a>
Part marking information	D <sup>2</sup> PAK (TO-263AB)	<a href="http://www.vishay.com/doc?95444">www.vishay.com/doc?95444</a>
	TO-262AA	<a href="http://www.vishay.com/doc?95443">www.vishay.com/doc?95443</a>
Packaging information	D <sup>2</sup> PAK (TO-263AB)	<a href="http://www.vishay.com/doc?96424">www.vishay.com/doc?96424</a>

### D<sup>2</sup>PAK

**DIMENSIONS** in millimeters and inches

Conforms to JEDEC® outline D<sup>2</sup>PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES		SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.				MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		e	2.54 BSC		0.100 BSC		
b2	1.14	1.78	0.045	0.070			H	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
c	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25 BSC		0.010 BSC		
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

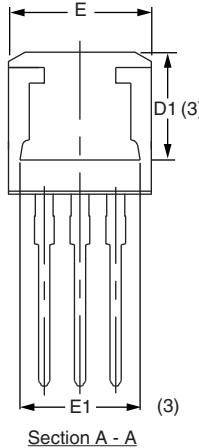
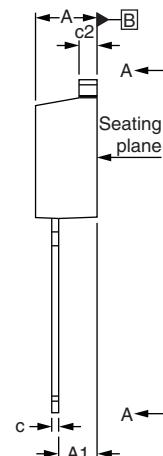
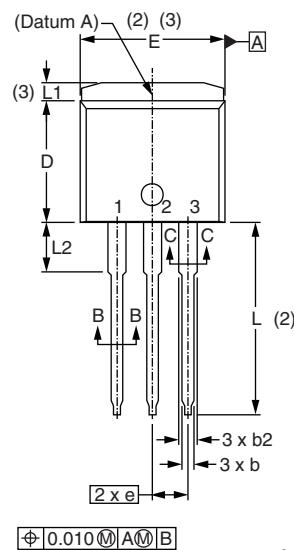
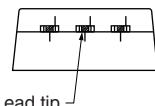
#### Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inches
- (7) Outline conforms to JEDEC® outline TO-263AB

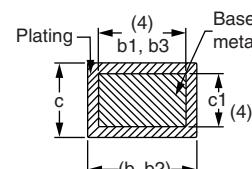
# TO-262AA

**DIMENSIONS** in millimeters and inches

## Modified JEDEC® outline TO-262


**Lead assignments**

**Diodes**

1. - Anode (two die/open (one die)
- 2., 4. - Cathode
3. - Anode


Section B - B and C - C

Scale: None

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.56	3.71	0.140	0.146	

**Notes**

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC® TO-262 except A1 (max.), b (min., max.), b1 (min.), b2 (max.), c (min.), c1(min.), c2 (max.), D (min.), E (max.), L1 (max.), L2 (min., max.)

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